

# Flexible Polymer Rectifying Diode on Plastic Foils with MoO<sub>3</sub> Hole Injection

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**Abstract**— In this work, a flexible solution processed polymer diode with a structure of aluminum/indacenodithiophene-benzothiadiazole (C<sub>16</sub>-IDT-BT)/molybdenum trioxide/gold was developed. A DC rectification ratio of  $7 \times 10^3$  was achieved at 2 V with a forward current density of 2.6 mA/cm<sup>2</sup> and a reverse current density of 0.37  $\mu$ A/cm<sup>2</sup>. The UV-ozone treated MoO<sub>3</sub> layer acted as a hole injection layer for the C<sub>16</sub>-IDT-BT layer to enhance the forward current density. The Au electrode with a higher work function compared to Ag was a superior anode for the polymer diode. The diode can be used as a blocking diode to allow the current to flow in the desired direction.

**Keywords**— organic, polymer diode, high DC rectification, solution processed, flexible electronics

## I. INTRODUCTION

Organic semiconductors, especially conjugated polymers, are intrinsically solution processable at rather low temperatures, making them attractive materials for a range of flexible and printable devices and systems [1]–[7]. These inexpensive, flexible and printable organic devices can be realized for various emerging applications such as the increasing demand for Internet of Things (IoT), wireless sensors and other ubiquitous small and embedded electronics. One of the most urgent demands of IoT is innovative, sustainable energy supply solutions to power billions of small electronic devices. Harvesting energy, or energy scavenging, from ambient sources such as light, radio frequency radiation, motion or thermal energy has massive appeal [8] and liberates the systems to be sustainably autonomous. The harnessed energy can be stored in novel energy storage devices, such as low-cost, environmentally friendly supercapacitors to form an autonomous energy module powering embedded sensors [9], [10].

As the simplest active electronic components, printable diodes based on organic semiconductors are important building blocks for low-cost energy harvesting modules. Printed organic polymer diodes have been used extensively as rectifiers (and voltage multipliers) to convert RF energy to DC power [7], [11]–[14]. Previously, we have demonstrated printable RF energy harvesters with gravure printed organic poly(triarylamine) PTAA diodes operating at 13.56 MHz [7], [9]. However, organic diodes like their Si-based counterparts can be used in many other applications such as an active matrix driving circuit [15]. Our aim in this work is to develop a DC blocking diode as a power protection unit

between the energy supply and the energy storage. The targeting voltage for the energy storage is around 2 V. Thus, the blocking diode should have a high current density at forward bias and a low reverse current density at reverse bias, in other words, a high DC rectification ratio at 2 V.

## II. EXPERIMENTS

Organic diodes were fabricated on both a SiO<sub>2</sub> coated wafer (31.500 Å  $\pm$ 5% Wet Thermal Oxide from Siegert Wafer) and a polyimide substrate (Kapton<sup>TM</sup> PV9100 from DuPont). The diode structure is shown in Fig. 1. A 45 nm thin layer of Al was E-beam evaporated through a shadow mask onto the substrate to form a cathode. A 5 mg/ml solution of indacenodithiophene-benzothiadiazole (C<sub>16</sub>-IDT-BT from Flexink) in 1,2-dichlorobenzene (from Sigma-Aldrich) was spin coated at 1500 rpm for 1 minute. The solution was preheated on a hotplate at 85 °C for 30 minutes to enhance the solubility before spin-coating. In addition, the Al layer was exposed to UV-ozone for 10 minutes to improve the wetting of C<sub>16</sub>-IDT-BT solution. The C<sub>16</sub>-IDT-BT layer was then cured on a hotplate at 150 °C for 30 minutes. A 2 nm thin layer of MoO<sub>3</sub> was thermal evaporated through a shadow mask as a hole injection layer. The MoO<sub>3</sub> layer was treated with UV-ozone for 10 minutes to tune the work function. A 100 nm Au or Ag layer was successively thermally evaporated through the same shadow mask to form an anode. All the evaporation materials were purchased from Kurt J. Lesker. The UV-ozone treatment was done with a PSD-UV from Novascan. All fabrication steps, except the UV-ozone treatment, were carried out in a nitrogen-filled glovebox. The organic diodes were taken outside the glovebox after fabrication with no encapsulation and all characterization was done in ambient environment. In addition, for Kelvin probe force microscopy (KPFM) measurement, a 100 nm Au layer followed by a 2 nm MoO<sub>3</sub> layer were thermal evaporated consecutively on a SiO<sub>2</sub> coated wafer to assemble a MoO<sub>3</sub> thin film sample.

The diode area was defined by the cross section of all the layers, which was approximately 0.02 cm<sup>2</sup>. The C<sub>16</sub>-IDT-BT

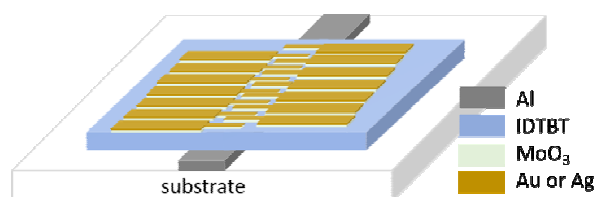


Fig. 1. Illustration of the diode structures.

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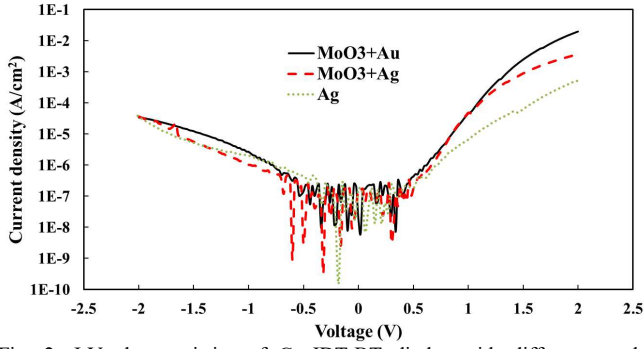


Fig. 2. J-V characteristics of  $C_{16}$ -IDT-BT diodes with different anode materials fabricated on  $SiO_2$  wafer.

layer thickness was determined using a Bruker Dektak XT stylus profilometer. The layer thickness was around 200 nm on the  $SiO_2$  wafer. The KPFM measurements were performed with a Bruker Dimension Icon in PeakForce KPFM mode. The current (current density)-voltage [I(J)-V] measurements of the organic diodes were carried out using a Keysight B1500A semiconductor analyzer connected to a probe station.

### III. RESULTS AND DISCUSSIONS

The intrinsic organic blocking diodes have a single semiconducting  $C_{16}$ -IDT-BT layer sandwiched between two metal electrodes, and modified versions with an additional buffer layer of  $MoO_3$  at the anode reported here. Due to the undoped organic semiconductor properties, the  $C_{16}$ -IDT-BT diodes can be considered as a metal-insulator-metal (MIM) diode. For p-type organic semiconductor  $C_{16}$ -IDT-BT, the ohmic injection contact is achieved by selecting a metal with a higher work function than the highest occupied molecular orbital (HOMO) level of the polymer. This metal, as an anode, injects charge carriers, i.e., holes for p-type semiconductor, into the polymer under forward bias. On the other hand, a cathode electrode is realized by having a lower work function metal compared to the HOMO level of the polymer. Their energy difference creates a barrier which blocks carriers to move under reverse bias. The reported HOMO level for  $C_{16}$ -IDT-BT is -5.4 eV [16]. This energy level is higher relative to most high work function metals such as Au (-5.1 eV), Pd (-5.12 eV), and Ni (-5.15 eV) [17], thus making it challenging to find a suitable anode electrode. Alternatively, transition metal oxide, such as molybdenum trioxide ( $MoO_3$ ), has been widely reported as anode buffer layer to successfully enhance hole injection in organic diodes due to its reported high work function of approximately -6.6 eV [12], [18]–[20]. Thus,  $MoO_3$  as the buffer layer was introduced in this report between the  $C_{16}$ -IDT-BT polymer and the anode metal. In addition, Al with a low work function around -4.2 eV [17] was fabricated as the cathode. The diodes were first fabricated on an  $SiO_2$  coated wafer before exploring flexible polyimide substrates too.

As one of the more common anode materials for p-type organic semiconductors, silver was initially tested as an anode material [12], [21]. Additionally, gold with a high work function was also selected for these initial tests. Surprisingly the fabricated polymer diodes with the Ag electrode without any buffer layer showed a current density of 0.48 mA/cm<sup>2</sup> and a passable DC rectification ratio of 12 at 2 V as shown in Fig. 2. On the other hand, the fabricated diodes with the Au anode offered no rectification. It is

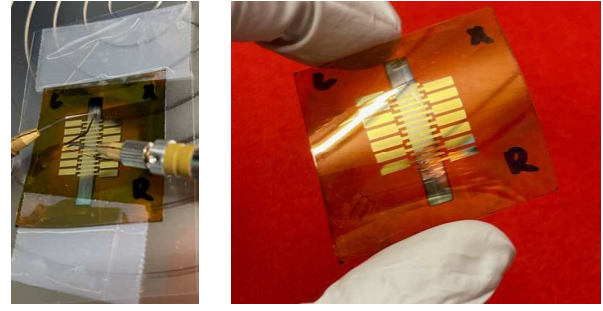


Fig.3. Photographs of the Al-( $C_{16}$ -ID-TBT)- $MoO_3$ -Au diodes on a flexible substrate.

interesting that Ag (4.7 eV) [17] with a lower work function than Au should theoretically act as an inferior hole injection anode, limiting the forward current. However, the J-V result showed passable forward current with Ag as the anode and no rectification with Au as the anode. We suspect the Ag electrode was oxidized during the fabrication process, modifying its work function, whereas the Au layer had poor contact properties, which could be due to a chemical reaction, diffusion, or poor adhesion of Au on the polymer.

Next, the  $MoO_3$  as the buffer layer at the anode was tested. As shown in Fig. 2, diodes with  $MoO_3$  as the buffer layer at the Ag anode yielded a significantly higher current density of 3.7 mA/cm<sup>2</sup> at 2 V. The forward current density increased approximately 8 times when adding the  $MoO_3$  layer at the Ag anode. This clearly demonstrated that the  $MoO_3$  layer can effectively enhance the hole injection into the polymer, thus increasing the forward current density of the diodes. Furthermore, as shown in Fig. 2, diodes with  $MoO_3$ -Au as the anode provided superior J-V characteristics, i.e., the highest forward current density while the reverse current density were similar to the Ag diodes. Compared to the diodes with  $MoO_3$ -Ag as the anode, the improved forward current of the diodes with the  $MoO_3$ -Au anode is likely due to the higher work function of the Au. In addition, the  $MoO_3$  as the buffer layer also prevented a direct contact between  $C_{16}$ -IDT-BT and Au which we attributed to the lack of rectification of the diodes with only Au as the anode. To sum up, the initial tests on the  $SiO_2$  coated wafers indicated that Al-( $C_{16}$ -ID-TBT)- $MoO_3$ -Au diodes offered the best performance. The forward and reverse current density were 19 mA/cm<sup>2</sup> at 2 V and 34  $\mu$ A/cm<sup>2</sup> at -2 V, respectively. The resulting DC rectification ratio was  $5.55 \times 10^2$  at 2 V.

Lastly, Al-( $C_{16}$ -ID-TBT)- $MoO_3$ -Au diodes were fabricated on flexible polyimide substrates, see Fig. 3. The fabrication steps are identical to the diodes on the  $SiO_2$  coated wafers reported here. The J-V characteristics of the polymer diodes on polyimide substrates are shown in Fig. 4. The forward and reverse current density of Al-( $C_{16}$ -ID-TBT)- $MoO_3$ -Au diodes on polyimide were 2.8 mA/cm<sup>2</sup> at 2 V and 0.31  $\mu$ A/cm<sup>2</sup> at -2 V, respectively. Compared to the wafer sample in Fig. 2, the forward current density of the polyimide sample decreased about 7 times while the reverse current dropped 100 times. This resulted an excellent DC rectification ratio of  $9 \times 10^3$  at 2 V. The drastic reduction of current density from the polyimide sample is likely due to a slightly thicker  $C_{16}$ -IDT-BT layer caused by the different surface energy and roughness of the polyimide substrate compared to the  $SiO_2$  coated wafer. Table I lists the major J-V parameters of diodes with different anode materials on both Si and polyimide substrates.

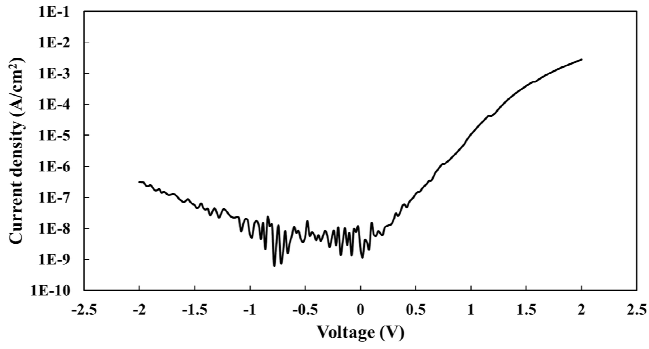


Fig. 4. J-V characteristics of Al-(C<sub>16</sub>-ID-TBT)-MoO<sub>3</sub>-Au diodes on a flexible substrate.

TABLE I. J-V PARAMETERS WITH DIFFERENT ANODE ELECTRODES

Anode	J @ 2 V (mA/cm <sup>2</sup> )	J @ -2 V (μA/cm <sup>2</sup> )	DC rectification ratio
Ag	0.48	38.6	12
MoO <sub>3</sub> -Ag	3.7	36.7	100
MoO <sub>3</sub> -Au	19	34.2	555
MoO <sub>3</sub> -Au on PI	2.8	0.31	9000

As a hole injection, anode buffer layer, the work function of thermally evaporated MoO<sub>3</sub> layers was investigated more thoroughly. To ensure a sufficient conductivity of the film, a 100 nm Au layer was deposited under the 2 nm MoO<sub>3</sub> layer on the SiO<sub>2</sub> coated wafer. In addition, a conductive copper tape was placed on top of the MoO<sub>3</sub> layer and the sample holder to ground the sample. KPFM was used to measure the resulting work function, and KPFM showed the mean potential was 1.23 V for the as-deposited MoO<sub>3</sub> sample and 1.51 V for the UV-ozone treated MoO<sub>3</sub> sample, relative to the reference electrode. The resulting work functions were extracted for the as-deposited and UV-ozone treated MoO<sub>3</sub> samples, which were 6.03 eV and 6.31 eV, respectively. These values are within the reported work function range of MoO<sub>3</sub> [22], [23]. However, since the KPFM measured the contact potential, also called surface potential difference, between the tip and a sample (or between the ground and a sample) in the form of a capacitor. In this case, the MoO<sub>3</sub>+Au layers acted as one of the plates of the capacitor. In other words, the measured potential represented all the induced charges at the surface which included the charges from the Au layer. Therefore, the calculated work function is not expected to be an accurate representation of the work function of the MoO<sub>3</sub> layer fabricated in this work. Nonetheless, the relative potential increase from 1.23 V to 1.51 V is entirely caused by the increased surface oxygen content of the MoO<sub>3</sub> layer from the UV-ozone treatment, which contributed to a 0.28 eV increase in work function of the treated MoO<sub>3</sub> layer. Indeed, the versatility of tuning work function of MoO<sub>3</sub> by inducing defects or changing the oxidation state of the metal cation is widely reported [18], [20]. In addition, the UV-ozone treatment removed a variety of contaminants from the MoO<sub>3</sub> layer surfaces to enable a consistent fabrication process. The RMS surface roughness as measured by AFM of the as-deposited and the UV-ozone treated MoO<sub>3</sub> samples is 1.11 nm and 0.892 nm, respectively. Similarly, KPMF results show the potential of UV-ozone treated Al increased by 0.6 V compared to the as-deposited Al layer which suggested the work function of Al changes from -4.2 eV to -4.8 eV. Therefore, the approximate energy

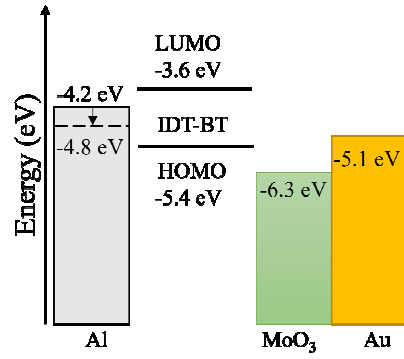


Fig. 5. Diagram of approximate energy levels of different layers.

levels for the various layers in the diodes are presented in Fig.5.

Besides the current density and the DC rectification ratio, another important parameter to evaluate for these diodes is the built-in voltage, which is sometimes referred as the turn-on voltage, or the threshold voltage. For undoped MIM type semiconductors, it is customarily defined as the work function difference of the two metal electrodes [24], [25]. However, in practice, several factors can affect the built-in voltage of the polymer diode such as the metal-organic interfaces formed by the printing process [26]–[28], and the trap states inside the organic layers [29]. Since the vacuum levels rarely align at the metal-organic interfaces, the relation of the work function and the energy alignment became more complicated [20], [30]. Therefore, in some studies the built-in voltage is determined as where the current starts to enter the space charge limited current (SCLC) region [24]. In other reports, the turn-on voltage is determined by the voltage where  $\log J$  has a sharp rise [31]. For the polymer diodes in this work, the diodes have not entered the SCLC region at 2 V, i.e., the current did not follow the Mott-Gurney equation [32]. In other words, the diodes were still in the diffusion and contact -limited current region [24] and the built-in voltage was larger than 2 V. Therefore, although the diodes offered high current density at low voltages ( $< 2$  V) as well as excellent DC rectification ratio, the electrodes and the buffer layer should be able to be further optimized to lower the built-in voltage.

#### IV. CONCLUSION

This work demonstrates solution processed organic polymer C<sub>16</sub>-ID-TBT diodes with different anode materials and a buffer layer. The UV-ozone treated MoO<sub>3</sub> layer as a hole injection buffer layer can significantly enhance the forward current density of the polymer diode. As an anode, Au with a higher work function yielded a larger forward current density compared to Ag. The polymer diode with a structure of Al-(C<sub>16</sub>-ID-TBT)-MoO<sub>3</sub>-Au was fabricated on a flexible polyimide substrate. At  $\pm 2$ V the forward current density was 2.6 mA/cm<sup>2</sup> whereas the reverse current was 0.37 μA/cm<sup>2</sup>. The resulting DC rectification was  $7 \times 10^3$ . All the measurements were performed in air. With further optimization of the MoO<sub>3</sub> layer, the IV characteristics of the polymer diodes can be improved.

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